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(54) DETERGENT FOR COPPER WIRING SEMICONDUCTOR SUBSTRATE

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a detergent capable of effectively removing impurities on the surface of a semiconductor having a copper wiring on the surface without causing corrosion and oxidation of the copper wiring and surface roughness and to provide a method for cleaning.

SOLUTION: This detergent for the surface of a semiconductor having a copper wiring on the surface comprises a nonionic surfactant containing a group of formula (1) in the molecule, for example, a nonionic surfactant of general formula 7 ($p+q+p'+q'$ is 1-20). This method for cleaning the surface of a semiconductor uses the detergent. This semiconductor having a copper wiring on the surface is obtained by treating the surface a semiconductor with the detergent.



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